

Product Compliance Declaration

Please see www.molex.com for the most up-to-date information.

Contact Information

Name Molex Product Compliance E-Mail Product.Compliance@molex.com

Part Information

Part Name CGrid SMT Hdr wLPeg 15 SAu 16Ckt Tub

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
CGrid SMT Hdr wLPeg 15 SAu 16Ckt Tub	Assembly		100	1.016465
COMPONENT CGrid Bkwy Hsg w/pgs 16/100Ckt	Component		37.0475	0.376575
LCP GF30 BLACK	Material		37.0475	0.376575
LCP	Substance		25.4517	0.258707
Carbon black	Substance	1333-86-4	0.3705	0.003766
GF-Fibre	Substance		11.1143	0.112973
Further Additives, not to declare	Substance	system	0.1111	0.00113
.440 X .0255 Sq Pin 15GOLD Plate	Assembly		62.9525	0.63989
.440 x .0255 Sq Bandolier Pin Unplated	Component		59.8151	0.608
Cartridge Brass 70% Unplated	Material		59.8151	0.608
Copper	Substance	7440-50-8	41.8706	0.4256
Zinc (metal)	Substance	7440-66-6	17.9445	0.1824
Gold Plating	Material		0.5758	0.005853

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Cobalt	Substance	7440-48-4	0.0014	0.000015
Nickel	Substance	7440-02-0	0.0014	0.000015
Gold	Substance	7440-57-5	0.5729	0.005824
Nickel Plating	Material		1.7315	0.0176
Nickel	Substance	7440-02-0	1.7313	0.017598
Further Additives, not to declare	Substance	system	0.0002	0.000002
Tin Plating	Material		0.83	0.008437
Tin	Substance	7440-31-5	0.83	0.008437

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2021)4569-DC (8 July 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

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Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
Lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
Lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes

^{*}Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	0015911162							
Part Name	CGrid SMT Hdr wLPeg 15 SAu 16Ckt Tub	(e)						
Part Information	on			Haz	zardous S	Substance	s	
Components			Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
CGrid SMT H	ldr wLPeg 15 SAu 16Ckt Tub		0	0	0	0	0	0
COMPONEN	T CGrid Bkwy Hsg w/pgs 16/100Ckt		0	0	0	0	0	0

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Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
.440 X .0255 Sq Pin 15GOLD Plate	0	0	0	0	0	0
.440 x .0255 Sq Bandolier Pin Unplated	0	0	0	0	0	0

Additional Information

Annex XVII to REACH (76/769/EEC)	Compliant
Regulation (EU) 2019/1021 (POP)	Compliant

Process Information

Component Plating / Surface Finish	MSn-Ni
Termination Base Alloy	Brass
Solder Alloy	N/A
Process Capability	REFLOW
Maximum Exposure Time (seconds)	030
Maximum Process Temperature (C)	260
Maximum Cycles at Reflow Temperature	003
J-STD-020 Moisture Sensitivity Level	N/A

Jan 2, 2022